

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT4504364

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT
NATURE OF CONVEYANCE:	Corrective Assignment to correct the ASSIGNOR, TIEN, YAO-WEI'S NAME previously recorded on Reel 034868 Frame 0406. Assignor(s) hereby confirms the CORRECTIVE ASSIGNMENT.
CONVEYING PARTY DATA	
Name	Execution Date
YAO-WEI TIEN	04/09/2013
CHI-HUNG LIAO	04/09/2013
MING-YI LEE	04/08/2013
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	NO. 8, LI-HSIN RD. 6
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK
City:	HSIN-CHU
State/Country:	TAIWAN
Postal Code:	300-77
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14611938
CORRESPONDENCE DATA	
Fax Number:	(214)200-0853
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	214-651-5000
Email:	ipdocketing@haynesboone.com
Correspondent Name:	HAYNES AND BOONE, LLP IP SECTION
Address Line 1:	2323 VICTORY AVENUE
Address Line 2:	SUITE 700
Address Line 4:	DALLAS, TEXAS 75219
ATTORNEY DOCKET NUMBER:	20120796/24061.2284US02
NAME OF SUBMITTER:	JANIE MARTINEZ-HOLM
SIGNATURE:	/Janie Martinez-Holm/
DATE SIGNED:	07/14/2017
Total Attachments: 5	

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PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
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EPAS ID: PAT3208537

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
YAN-WEI TIEN	<u>YAO-WEI TIEN</u>	04/09/2013
	CHI-HUNG LIAO	04/09/2013
	MING-YI LEE	04/08/2013
RECEIVING PARTY DATA		
Name:	Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC")	
Street Address:	No. 8, Li-Hsin Rd. 6	
Internal Address:	Science-Based Industrial Park	
City:	Hsin-Chu	
State/Country:	TAIWAN	
Postal Code:	300-77	
PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	14611938	
CORRESPONDENCE DATA		
Fax Number:	(214)200-0853	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
Phone:	5128678528	
Email:	ipdocketing@haynesboone.com	
Correspondent Name:	HAYNES AND BOONE, LLP	
Address Line 1:	IP SECTION, 2323 VICTORY AVENUE	
Address Line 2:	SUITE 700	
Address Line 4:	DALLAS, TEXAS 75219	
ATTORNEY DOCKET NUMBER:	20120796/24061.2284US02	
NAME OF SUBMITTER:	Y. KIM REYES	
SIGNATURE:	/Y. Kim Reyes/	
DATE SIGNED:	02/02/2015	
Total Attachments: 2		
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Docket No.: 2012-0796 / 24061.2284

Customer No.: 42717

ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|---------------|----|---|
| (1) | Yao-Wei Tien | of | No. 24, Alley 1, Lane 273, Linsen Road
Hualien City, Hualien County 970, Taiwan R.O.C. |
| (2) | Chi-Hung Liao | of | No. 11, Changlong Street
Sanchong City Taipei County 241, Taiwan R.O.C. |
| (3) | Ming-Yi Lee | of | No. 8, Li Xing 6 Road
Xin Zhu Shi, Taiwan R.O.C. |

have invented certain improvements in

SYSTEM AND METHOD FOR DEFECT ANALYSIS OF A SUBSTRATE

for which we have executed an application for Letters Patent of the United States of America, filed on November 9, 2012, and assigned application number 13/673,664; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do

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everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Yao-Wei Tien

Residence Address: No. 24, Alley 1, Lane 273, Linsen Road
Hualien City, Hualien County 970, Taiwan R.O.C.

Dated: Yao-Wei Tien 4/9/2013

4/9/2013 Yao-Wei Tien
Inventor Signature

Inventor Name: Chi-Hung Liao

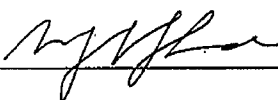
Residence Address: No. 11, Changlong Street
Sanchong City Taipei County 241, Taiwan R.O.C.

Dated: 4/9/2013

Chi-Hung Liao
Inventor Signature

Inventor Name: Ming-Yi Lee

Residence Address: No. 8, Li Xing 6 Road
Xin Zhu Shi, Taiwan R.O.C.

Dated:  04/08/2013


Inventor Signature